L	Hits	Search Text	DB	Time stamp
Number				_
-	3461	((438/118) or (438/119) or (438/612) or (438/615) or (438/616) or (438/617)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/09/28 16:08
-	928	(((438/118) or (438/119) or (438/612) or (438/615) or (438/616) or (438/617)).CCLS.) and (metal same chip)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/24 03:02
_	669	((((438/118) or (438/119) or (438/612) or (438/615) or (438/616) or (438/617)).CCLS.) and (metal same chip)) and ((wire or wir\$3) same bond\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/24 03:03
-	386	<pre>(((((438/118) or (438/119) or (438/612) or (438/615) or (438/616) or (438/617)).CCLS.) and (metal same chip)) and ((wire or wir\$3) same bond\$3)) and interconnect\$3</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/24 03:04
-	141	<pre>((((((438/118) or (438/119) or (438/612) or (438/615) or (438/616) or (438/617)).CCLS.) and (metal same chip)) and ((wire or wir\$3) same bond\$3)) and interconnect\$3) and ((copper or cu) same interconnect\$3)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 03:04
-	139	<pre>((((((((438/118) or (438/119) or (438/612) or (438/615) or (438/616) or (438/617)).CCLS.) and (metal same chip)) and ((wire or wir\$3) same bond\$3)) and interconnect\$3) and ((copper or cu) same interconnect\$3)) and (gold or au or aluminum or al or aluminium)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 03:05
_	74	· ·	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 03:05
-	24	((((((((438/118) or (438/119) or (438/612) or (438/615) or (438/616) or (438/617)).CCLS.) and (metal same chip)) and ((wire or wir\$3) same bond\$3)) and interconnect\$3) and ((copper or cu) same interconnect\$3)) and (gold or au or aluminum or al or aluminum)) and (substrate same (silicon or si or gaas or inp))) and (ultrasonic or thermosonic or welding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 03:06
-	15	(((((((((438/118) or (438/119) or (438/612) or (438/615) or (438/616) or (438/617)).CCLS.) and (metal same chip)) and ((wire or wir\$3) same bond\$3)) and interconnect\$3) and ((copper or cu) same interconnect\$3)) and (gold or au or aluminum or al or aluminium)) and (substrate same (silicon or si or gaas or inp))) and (bond\$3 same(ultrasonic or thermosonic or welding))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 03:06